TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

TPCF8201

Notebook PC Applications Portable Equipment Applications

• Low drain-source ON resistance: RDS (ON) = 38 m Ω (typ.)

• High forward transfer admittance: $|Y_{fs}| = 5.4 \text{ S (typ.)}$

• Low leakage current: $IDSS = 10 \mu A \text{ (max) (VDS} = 20 \text{ V)}$

• Enhancement-model: $V_{th} = 0.5 \text{ to } 1.2 \text{ V}$

 $(V_{DS} = 10 \text{ V}, I_{D} = 200 \text{ }\mu\text{A})$

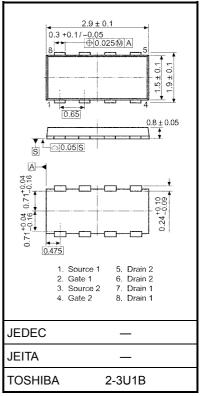
Maximum Ratings ($Ta = 25^{\circ}C$)

Cha	Symbol	Rating	Unit		
Drain-source volta	V_{DSS}	20	V		
Drain-gate voltage	Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V	
Gate-source voltage	V _{GSS}	±12	V		
Drain current	DC (Note 1)	I _D	3	A	
Drain current	Pulse (Note 1)	I_{DP}	20 20 ±12	Α	
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.35	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.12		
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	0.53		
(t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.33		
Single pulse avala	nche energy (Note 4)	E _{AS}	1.46	mJ	
Avalanche current		I _{AR}	1.5	Α	
Repetitive avalanc Single-device value	E _{AR}	0.11	mJ		
Channel temperatu	T _{ch}	150	°C		
Storage temperatu	T _{stg}	-55~150	°C		

Note: For (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) and (Note 6), please refer to the next page.

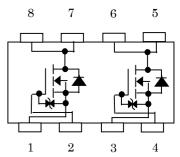
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

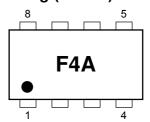


Weight: 0.011 g (typ.)

Circuit Configuration



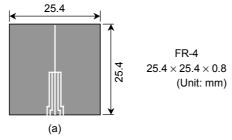
Marking (Note 6)

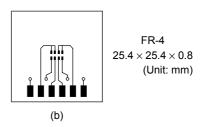


Thermal Characteristics

Characteristics		Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	92.6	°C/W	
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	111.6		
Thermal resistance,	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	235.8	°C/W	
channel to ambient (t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	378.8	C/VV	

- Note 1: Please use devices on condition that the channel temperature is below 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a)
- (b) Device mounted on a glass-epoxy board (b)





- Note 3: a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
 - b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).
- Note 4: $V_{DD} = 16 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 0.5 mH, $R_G = 25 \Omega$, $I_{AR} = 1.5 \text{ A}$
- Note 5: Repetitive rating; Pulse width limited by Max. Channel temperature.
- Note 6: Black round marking "● " locates on the left lower side of parts number marking "F4A" indicates terminal No. 1.

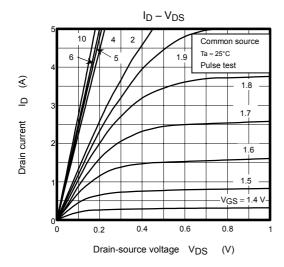
Electrical Characteristics (Ta = 25° C)

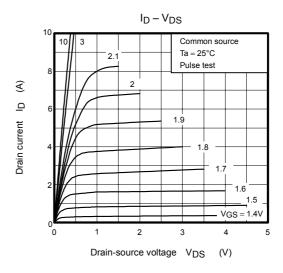
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	_	_	10	μΑ
Drain-source brea	V (BR) DSS		$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	20	_	_	V
Drain-source breakdown voltage		V _{(BR)DSX}	$I_D = 10$ mA, $V_{GS} = -12$ V	8	_	_	V
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, I_D = 200 \mu\text{A}$	0.5	_	1.2	٧
		R _{DS} (ON)	$V_{GS} = 2.0 \text{ V}, I_D = 1.5 \text{ A}$	_	62	100	mΩ
Drain-source ON	resistance	R _{DS} (ON)	$V_{GS} = 2.5 \text{ V}, I_D = 1.5 \text{ A}$	_	50	66	
		R _{DS} (ON)	V _{GS} = 4.5 V, I _D = 1.5 A	_	38	49	
Forward transfer admittance		Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 1.5 \text{ A}$	2.7	5.4	_	S
Input capacitance		C _{iss}		_	590	_	
Reverse transfer	capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	70	_	pF
Output capacitance		C _{oss}		_	85	_	
Switching time	Rise time	t _r	V _{DD} ≈ 10 V	_	3.0	_	
	Turn-on time	t _{on}		_	7.5	_	ns
	Fall time	t _f		_	4.4	_	
	Turn-off time	t _{off}	Duty ≦ 1%, t _w = 10 μs	_	26	_	
Total gate charge (gate-source plus gate-drain) Qg		Qg	$V_{DD} \approx 16 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 3.0 \text{ A}$		7.5	_	
Gate-source charge1		Q _{gs1}			1.3		nC
Gate-drain ("miller") charge		Q _{gd}		_	2.1		

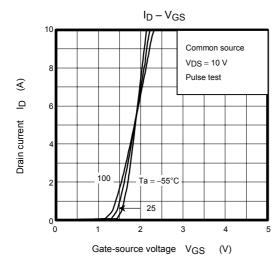
Source-Drain Ratings and Characteristics (Ta = 25°C)

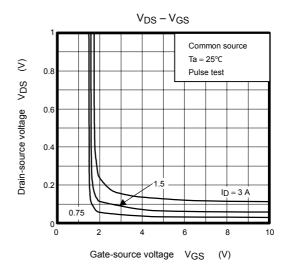
Characterist	ics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	12	Α
Forward voltage (diode)		V _{DSF}	$I_{DR} = 3.0 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V

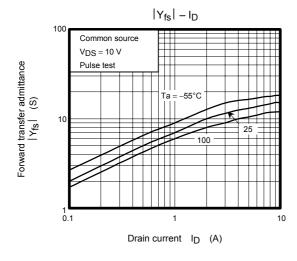
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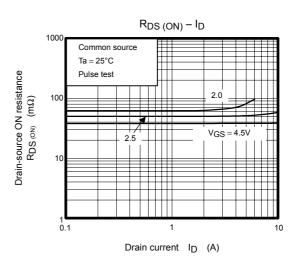


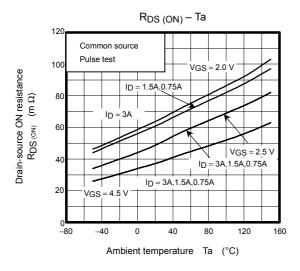


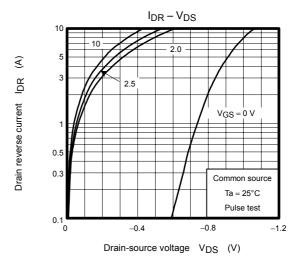


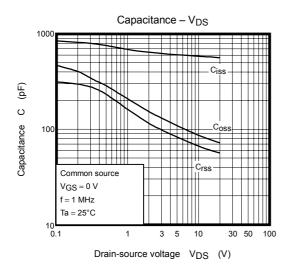


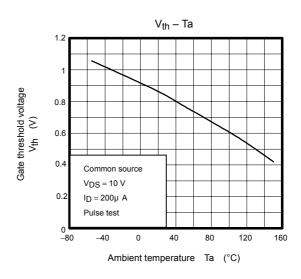


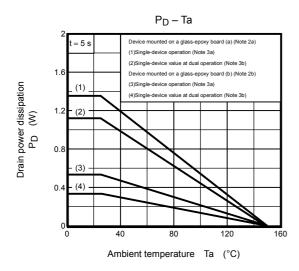


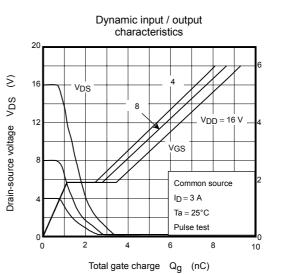


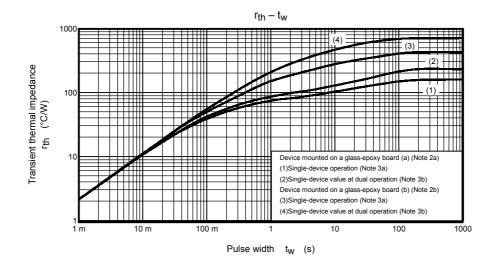


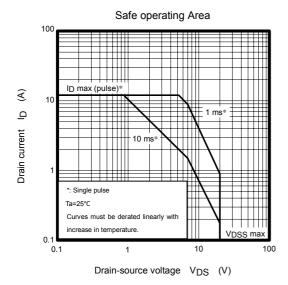












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